

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPP80P03P4L-04	**Issued**	08. April 2022
MA#	MA005709947		
Package	PG-TO220-3-1	**Weight***	2037.20 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.029	0.20	0.20	1977	1977
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	iron	7439-89-6	0.816	0.04		401	
	non noble metal	copper	7440-50-8	815.335	40.03	40.08	400223	400744
wire	non noble metal	aluminium	7429-90-5	7.991	0.39	0.39	3923	3923
encapsulation	inorganic material	zincoxide	1314-13-2	5.936	0.29		2914	
	miscellaneous	miscellaneous	-	23.744	1.17		11655	
	plastics	epoxy resin	-	89.042	4.37		43708	
	inorganic material	silicondioxide	60676-86-0	474.890	23.31	29.14	233109	291386
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10535	10535
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	120	121
solder	non noble metal	tin	7440-31-5	0.065			32	
	noble metal	silver	7440-22-4	0.081			40	
	non noble metal	lead	7439-92-1	3.085	0.15	0.15	1514	1586
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	iron	7439-89-6	0.590	0.03		290	
	non noble metal	copper	7440-50-8	589.466	28.94	28.98	289351	289728
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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